MECHANICAL CASE OUTLINE

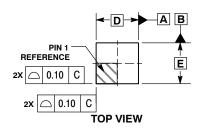
PACKAGE DIMENSIONS





XDFN6 1.40x1.35, 0.4P CASE 711AV ISSUE A

DATE 04 JUN 2014



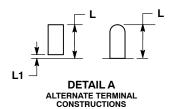
DETAIL B

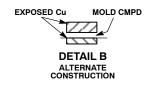
SIDE VIEW

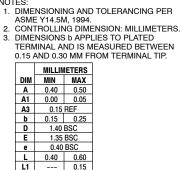
// 0.10 C

□ 0.08 C

6X







NOTES:

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

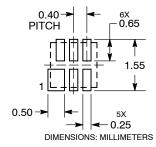
M = Date Code

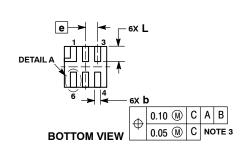
= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT





SEATING PLANE

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